

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (U-MOSIII)

TPCS8211

Lithium Ion Battery Applications

Notebook PC Applications

Portable Equipment Applications

- Small footprint due to small and thin package
- Low drain-source ON resistance: $R_{DS(ON)} = 16 \text{ m}\Omega$ (typ.)
- High forward transfer admittance: $|Y_{fs}| = 11 \text{ S}$ (typ.)
- Low leakage current: $I_{DSS} = 10 \text{ }\mu\text{A}$ (max) ($V_{DS} = 20 \text{ V}$)
- Enhancement mode: $V_{th} = 0.5 \sim 1.2 \text{ V}$ ($V_{DS} = 10 \text{ V}$, $I_D = 200 \text{ }\mu\text{A}$)

Absolute Maximum Ratings ($T_a = 25^\circ\text{C}$)

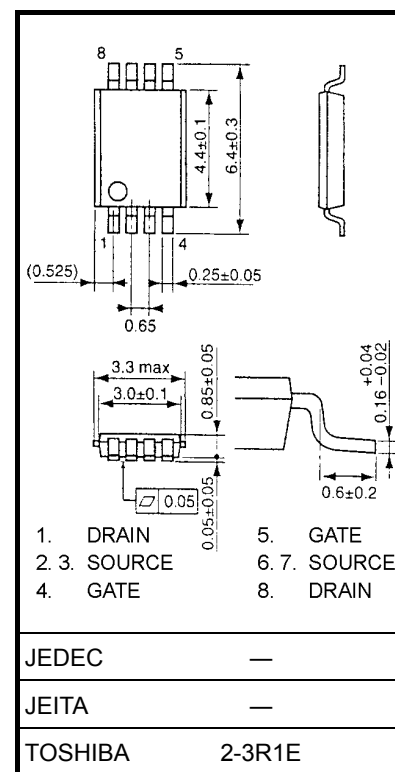
Characteristics		Symbol	Rating	Unit
Drain-source voltage		V_{DSS}	20	V
Drain-gate voltage ($R_{GS} = 20 \text{ k}\Omega$)		V_{DGR}	20	V
Gate-source voltage		V_{GSS}	± 12	V
Drain current	DC (Note 1)	I_D	6	A
	Pulse (Note 1)	I_{DP}	24	
Drain power dissipation ($t = 10 \text{ s}$) (Note 2a)	Single-device operation (Note 3a)	P_D (1)	1.1	W
	Single-device value at dual operation (Note 3b)	P_D (2)	0.75	
Drain power dissipation ($t = 10 \text{ s}$) (Note 2b)	Single-device operation (Note 3a)	P_D (1)	0.6	W
	Single-device value at dual operation (Note 3b)	P_D (2)	0.35	
Single pulse avalanche energy (Note 4)		E_{AS}	46.8	mJ
Avalanche current		I_{AR}	6	A
Repetitive avalanche energy Single-device value at dual operation (Note 2a, 3b, 5)		E_{AR}	0.075	mJ
Channel temperature		T_{ch}	150	$^\circ\text{C}$
Storage temperature range		T_{stg}	$-55 \sim 150$	$^\circ\text{C}$

Note: (Note 1), (Note 2), (Note 3), (Note 4) and (Note 5): See the next page.

Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

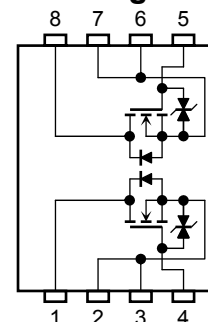
This transistor is an electrostatic-sensitive device. Please handle with caution.

Unit: mm



Weight: 0.035 g (typ.)

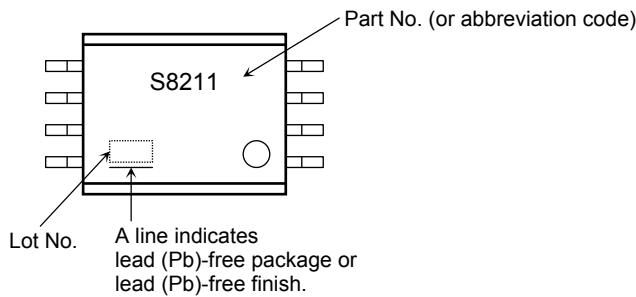
Circuit Configuration



Thermal Characteristics

Characteristics		Symbol	Max	Unit
Thermal resistance, channel to ambient (t = 10 s)	Single-device operation (Note 3a)	$R_{th (ch-a) (1)}$	114	°C/W
	Single-device value at dual operation (Note 3b)	$R_{th (ch-a) (2)}$	167	
Thermal resistance, channel to ambient (t = 10 s)	Single-device operation (Note 3a)	$R_{th (ch-a) (1)}$	208	°C/W
	Single-device value at dual operation (Note 3b)	$R_{th (ch-a) (2)}$	357	

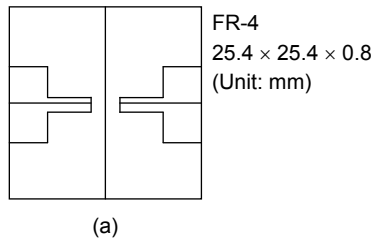
Marking (Note 6)



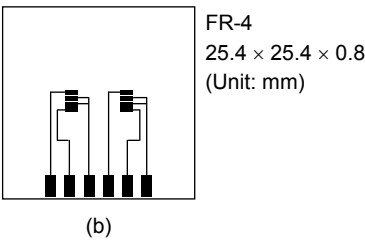
Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2:

a) Device mounted on a glass-epoxy board (a)



b) Device mounted on a glass-epoxy board (b)



Note 3:

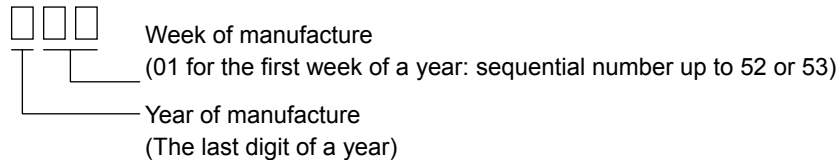
- a) The power dissipation and thermal resistance values are shown for a single device (During single-device operation, power is only applied to one device.).
- b) The power dissipation and thermal resistance values are shown for a single device (During dual operation, power is evenly applied to both devices.).

Note 4: $V_{DD} = 16\text{ V}$, $T_{ch} = 25^\circ\text{C}$ (initial), $L = 1.0\text{ mH}$, $R_G = 25\ \Omega$, $I_{AR} = 6\text{ A}$

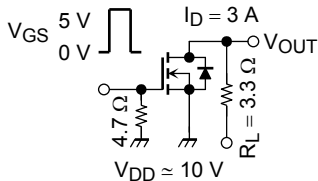
Note 5: Repetitive rating: pulse width limited by maximum channel temperature.

Note 6: $\circ$ on lower right of the marking indicates Pin 1.

※ Weekly code: (Three digits)

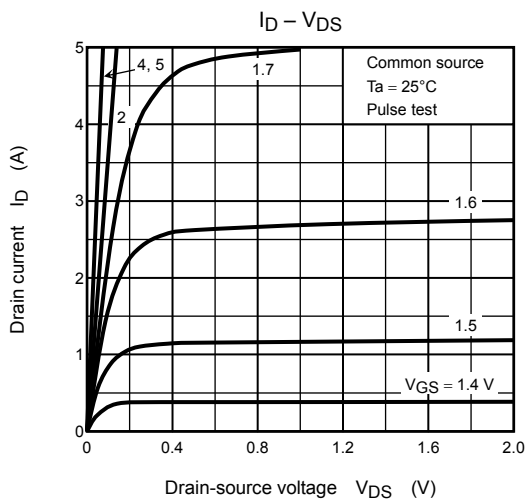
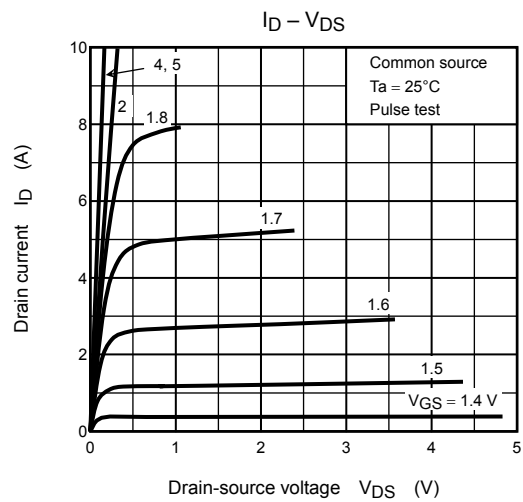
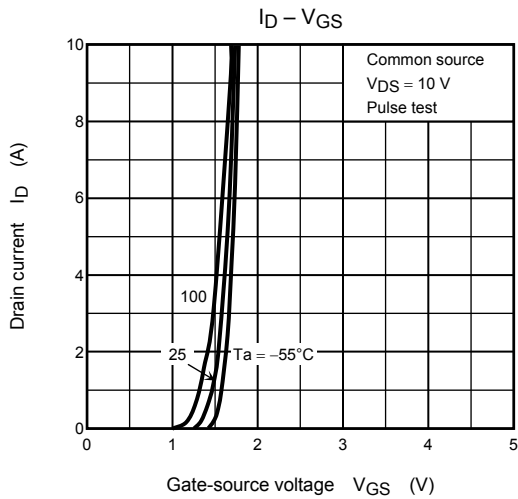
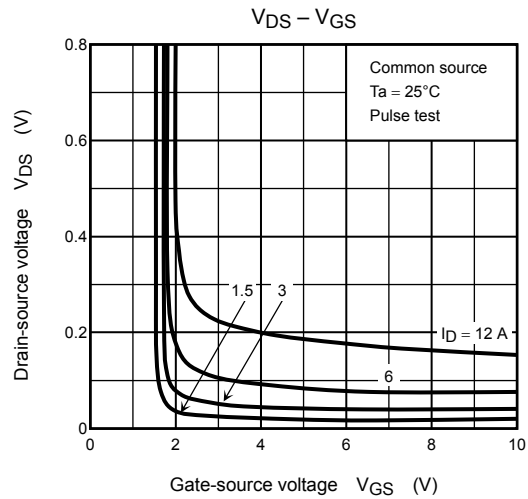
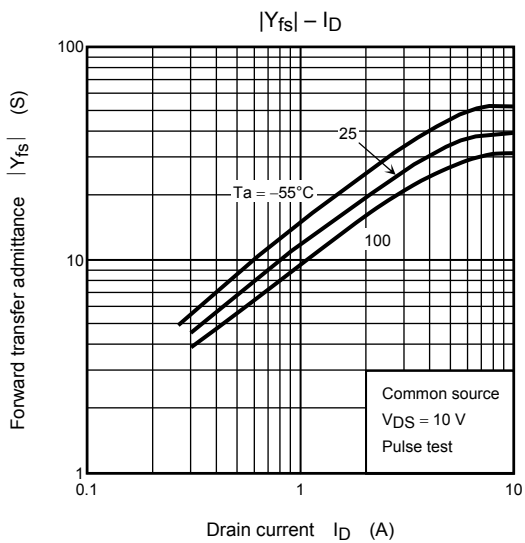
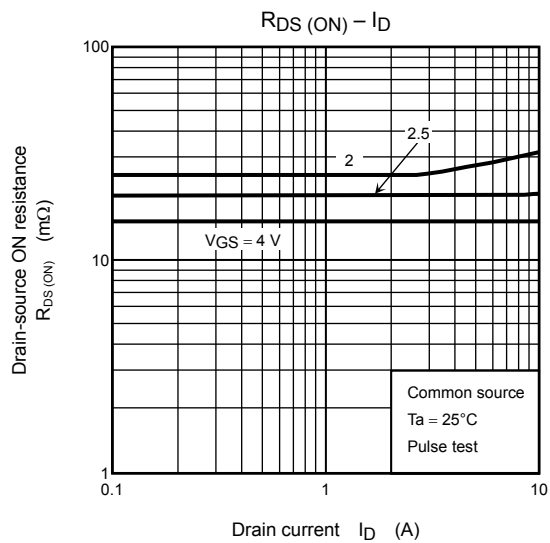


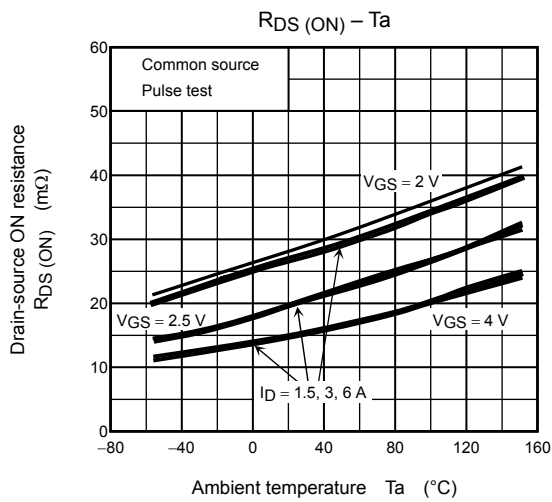
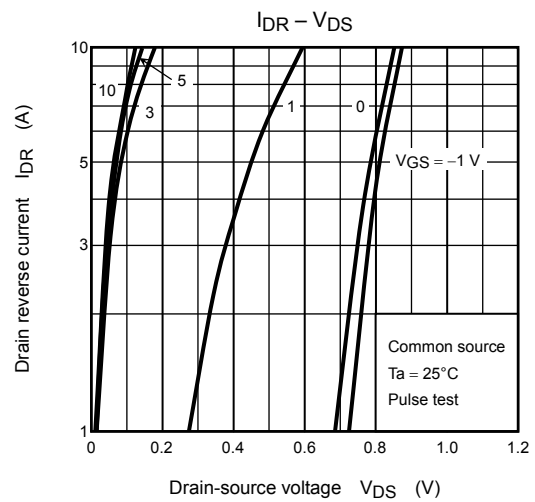
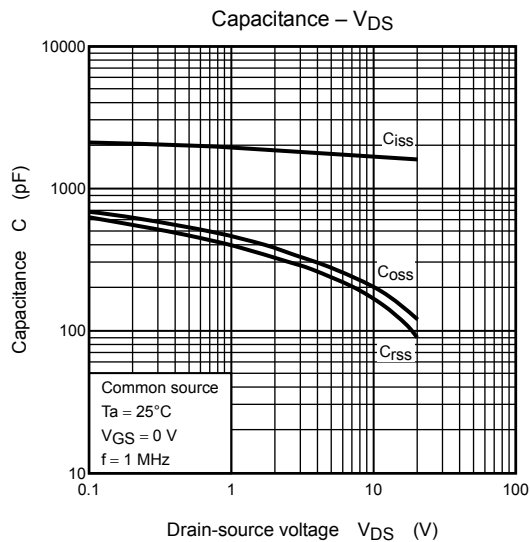
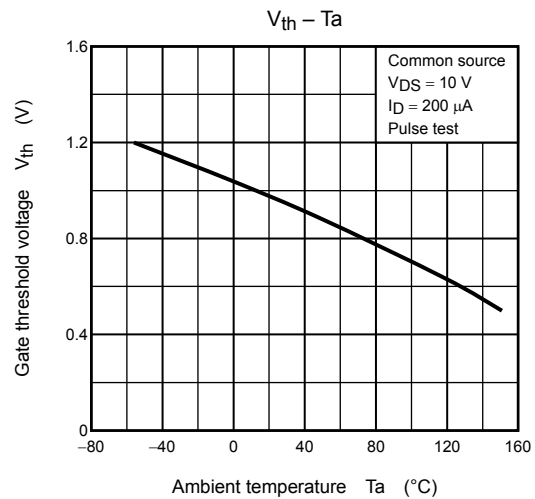
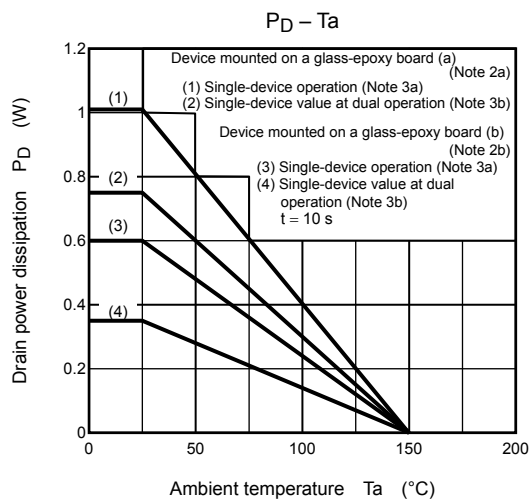
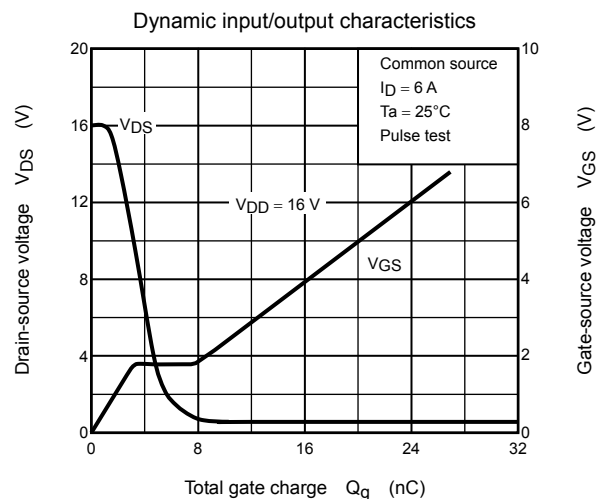
Electrical Characteristics (Ta = 25°C)

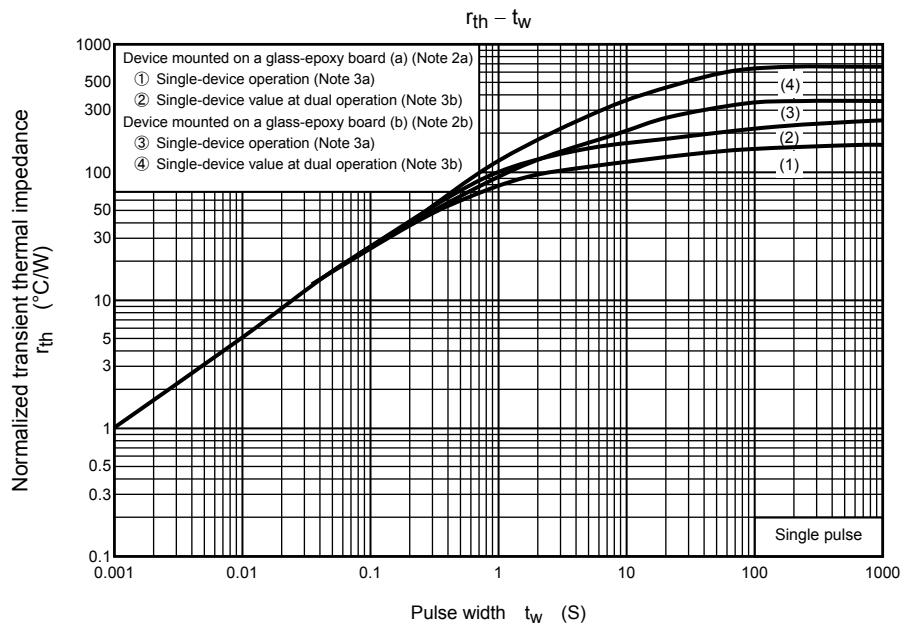
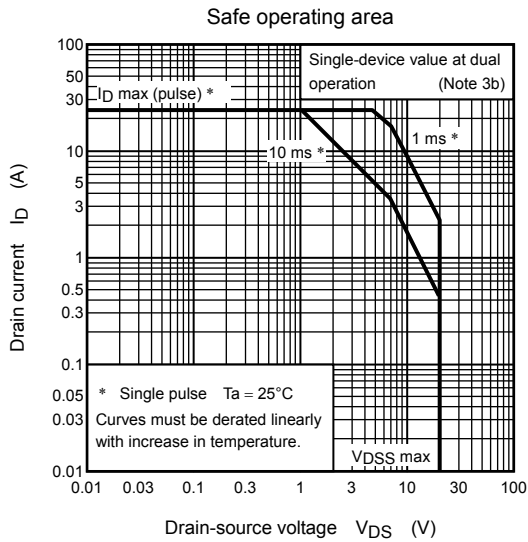
Characteristics		Symbol	Test Condition	Min	Typ.	Max	Unit
Gate leakage current		I _{GSS}	V _{GS} = ±10 V, V _{DS} = 0 V	—	—	±10	μA
Drain cut-OFF current		I _{DSS}	V _{DS} = 20 V, V _{GS} = 0 V	—	—	10	μA
Drain-source breakdown voltage	V _(BR) DSS	I _D = 10 mA, V _{GS} = 0 V	20	—	—	V	
	V _(BR) DSX	I _D = 10 mA, V _{GS} = -12 V	8	—	—		
Gate threshold voltage		V _{th}	V _{DS} = 10 V, I _D = 200 μA	0.5	—	1.2	V
Drain-source ON resistance		R _{DS} (ON)	V _{GS} = 2.0 V, I _D = 4.2 A	—	26	45	mΩ
			V _{GS} = 2.5 V, I _D = 4.2 A	—	21	29	
			V _{GS} = 4.0 V, I _D = 4.8 A	—	16	24	
Forward transfer admittance		Y _{fs}	V _{DS} = 10 V, I _D = 3.0 A	5.5	11	—	S
Input capacitance		C _{iss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	—	1590	—	pF
Reverse transfer capacitance		C _{rss}		—	180	—	
Output capacitance		C _{oss}		—	200	—	
Switching time	Rise time	t _r	 <p>V_{GS} 5 V 0 V I_D = 3 A V_{OUT} 4.7 Ω V_{DD} ≈ 10 V R_L = 3.3 Ω Duty ≤ 1%, t_w = 10 μs</p>	—	6.4	—	ns
	Turn-ON time	t _{on}		—	22	—	
	Fall time	t _f		—	10	—	
	Turn-OFF time	t _{off}		—	42	—	
Total gate charge (gate-source plus gate-drain)		Q _g	V _{DD} ≈ 16 V, V _{GS} = 5 V, I _D = 6 A	—	20	—	nC
Gate-source charge 1		Q _{gs1}		—	3.5	—	
Gate-drain ("miller") charge		Q _{gd}		—	4.5	—	

Source-Drain Ratings and Characteristics (Ta = 25°C)

Characteristics		Symbol	Test Condition	Min	Typ.	Max	Unit
Drain reverse current	Pulse (Note 1)	I_{DRP}	—	—	—	24	A
Forward voltage (diode)		V_{DSF}	$I_{DR} = 6 \text{ A}, V_{GS} = 0 \text{ V}$	—	—	-1.2	V







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